

Translation of the attached sheet (Japanese text portions only)  
Background Art Information

Patent No./Publication	Inventor(s)/Author(s)	Date etc
Jpn. Pat. Appln. KOKAI Publication No. 3-224295; Oki Electric Industry Co., Ltd.; Published October 3, 1991		
*Concise Explanation		
This document discloses, as described in the prior art section of the specification of the present invention, an assembly structure of a modem box in which the substrate is covered by a molded upper and lower cover (including side surfaces) made of a resin material having an elasticity, and by a front panel and a rear panel.		
Jpn. Pat. Appln. KOKAI Publication No. 2002-16524; Published January 18, 2002, "Transmission/Reception Integrated Type High Frequency Device"; Toshiba		
*Concise Explanation		
This document discloses, as described in the prior art section of the specification of the present invention, a transmission/reception integrated type high frequency device with an improved communication quality that is achieved by covering the four surfaces of the substrate with which the coaxial cable mount portion is integrally provided, by shield plates.		
Prior Applications of Inventors or of Kabushiki Kaisha Toshiba (Assignee)		
Application No.	Toshiba Reference	Country Agent memo
Inventor(s)		
Signature & Date		

Patent engineer's comment on inventor's information or patent engineer's information

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Checked by

Dated

Toshiba Reference

Japanese Agent's Ref

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